DISCRETE SEMICONDUCTORS



Product specification

September 2019



Product specification

BT152B series

GENERAL DESCRIPTION

Planar passivated thyristors in a plastic envelope suitable for surface mounting. intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

PINNING - SOT404

PIN

1

2

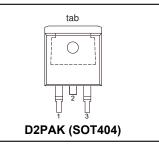
3

mb

QUICK REFERENCE DATA

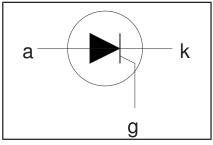
SYMBO	PARAMETER	MAX.	MAX.	MAX.	UNIT	
V _{drm} , V _{rrm} I _{t(av)} I _{t(rms)} I _{tsm}	BT152B- Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current	400R 450 13 20 200	600R 650 13 20 200	800R 800 13 20 200	V A A A	

DESCRIPTION cathode anode



PIN CONFIGURATION

SYMBOL



LIMITING VALUES

gate

anode

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V _{DRM}	Repetitive peak off-state voltages		-	-400R 450 ¹	-600R 650 ¹	-800R 800	V
I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{mb} \le 103$ °C all conduction angles half sine wave; $T_j = 25$ °C prior to surge	-		13 20		A A
l ² t	l ² t for fusing	t = 10 ms t = 8.3 ms t = 10 ms	- -		200 220 200		A A A²s
di _T /dt	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 50 \text{ A}; I_G = 0.2 \text{ A}; dI_G/dt = 0.2 \text{ A};$	-		200		A/μs
I _{GM} V _{GM} V _{RGM} P _{GM}	Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power		- - -		5 5 5 20		A V V W
P _{G(AV)} T _{stg} T _j	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	-40 -		0.5 150 125		ů °C °C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance		-	-	1.1	K/W
R _{th i-a}	junction to mounting base Thermal resistance junction to ambient	minimum footprint, FR4 board	-	55	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

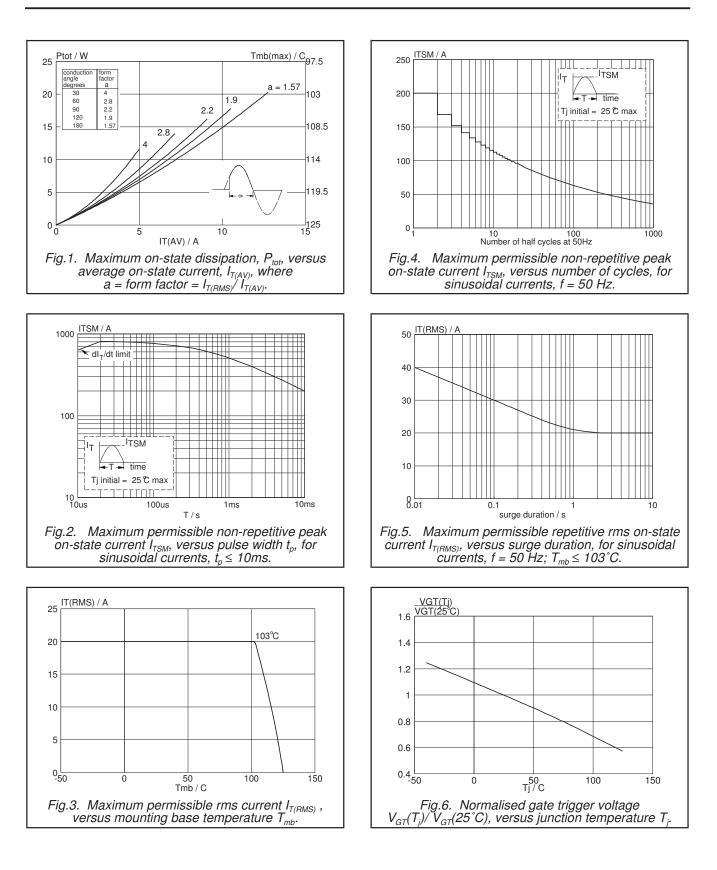
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-	3	32	mA
	Latching current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	25	80	mA
	Holding current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	15	60	mA
I _H V _⊤	On-state voltage	$I_{T} = 40 \text{ A}$	-	1.4	1.75	V
V _{GT}	Gate trigger voltage	$\dot{V}_{\rm D} = 12 \text{ V}; I_{\rm T} = 0.1 \text{ A}$	-	0.6	1.5	V
<u> </u>		$V_{D} = V_{DRM(max)}; I_{T} = 0.1 \text{ A}; T_{j} = 125 \text{ °C}$	0.25	0.4	-	V
I _D , I _R	Off-state leakage current	$V_D = V_{DRM(max)}; V_R = V_{RRM(max)}; T_j = 125 \text{°C}$	-	0.2	1.0	mA

DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

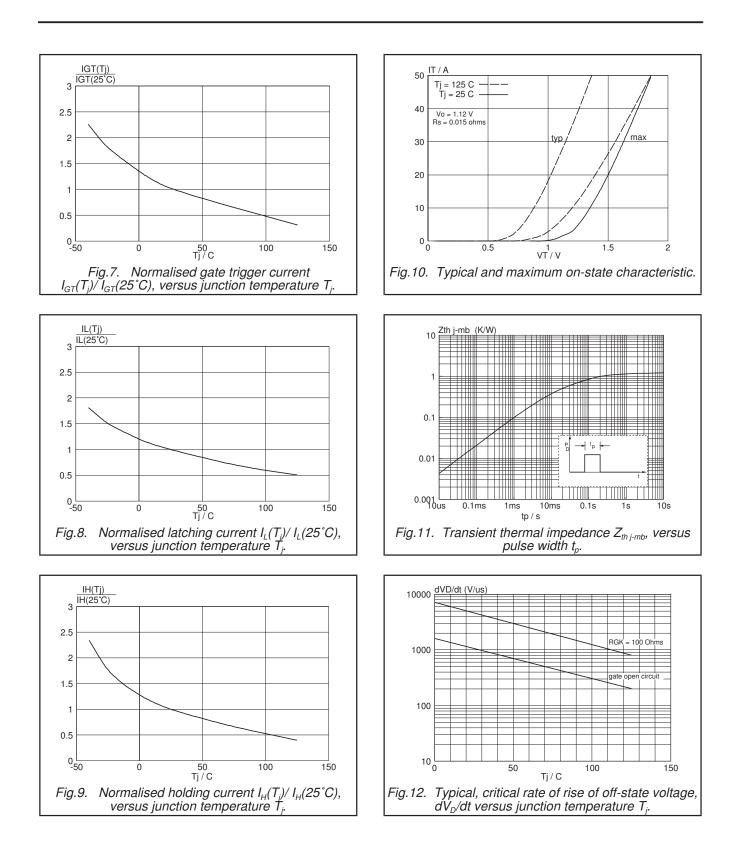
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform gate open circuit	200	300	-	V/µs
t _{gt}	Gate controlled turn-on	$V_D = V_{DRM(max)}$; $I_G = 0.1$ Å; $dI_G/dt = 5$ Å/µs; $I_{TM} = 40$ Å	-	2	-	μs
t _q	Circuit commutated turn-off time		-	70	-	μs

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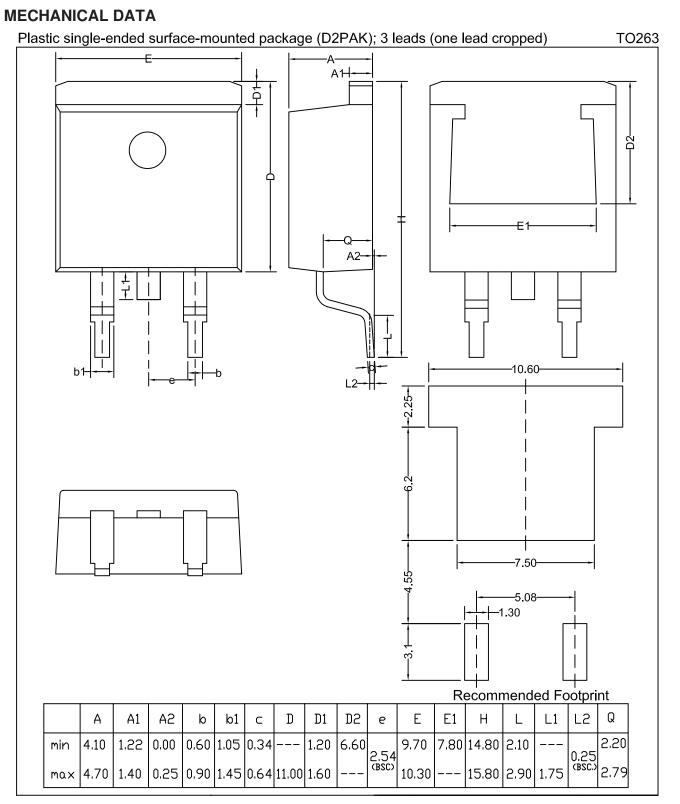
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Thyristors



BT152B series

Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <u>http://www.ween-semi.com</u>.

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